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Search scope: US Granted US Applications JP (bibliographic data only)

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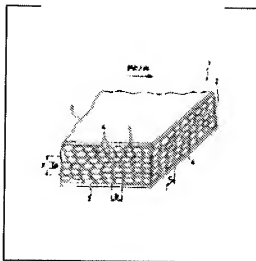
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JP10000748 A
POLYPROPYLENE-BASED RESIN FOAM
LAMINATED SHEET AND MOLDING BODY
THEREOF
JSP CORP

Abstract:

PROBLEM TO BE SOLVED: To improve characteristics such as lightweight properties, washability, toughness, rigidity or the like by a method wherein a foam laminated sheet, which has the specified flexural modulus and is suitable for a the stock such as a returnable container or the like, is produced by laminating a synthetic resin film having the specified tensile strength onto one side of a plate-like polypropylene-based resin foam having the specified density.



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SOLUTION: This foam laminated sheet 1 suitably used for a simple packaging box such as a returnable container or the like is produced by laminating synthetic resin film 3 onto both the sides of a plate-like polypropylene-based resin foam as to have the flexural modulus of $900\text{--}3,500\text{kg/cm}^2$. In this plate-like polypropylene-based resin foam 2, the shape of each of bubbles existing within the portion, which exceeds 25% of the whole thickness from both the surfaces of the foam, satisfies the following formulae: $0.40 \leq A/B \leq 1.0$, $0.4 \leq A/C \leq 1.0$ and $0.2 \leq (A+B+C)/3 \leq 1.5$, in which A, B and C represent respectively average bubble diameter in thickness direction, extrusion direction and widthwise direction. The synthetic resin film 3, for which orientated polypropylene-based resin film is suitable, is used under the condition having the tensile strength of 10kg/mm^2 or more and the thickness of $5\text{--}60\mu\text{m}$.

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Current IPC-R:

	invention	additional
Advanced	B32B000518 20060101	B29K002300 20060101
	B29C005114 20060101	B29L000900 20060101
	B32B002700 20060101	
	B32B002732 20060101	
	invention	additional
Core	B32B000518 20060101	
	B29C005114 20060101	
	B32B002700 20060101	
	B32B002732 20060101	

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Patents Citing This One:

- EP1174263 A1 20020123 SEKISUI CHEMICAL CO., LTD.
- JP3884670 B2 20070221
- US5091340 A 19920225 NEC Corporation
- US7063768 B2 20060620 Sekisui Chemical Co., Ltd.
- EP1174263 B1 20030618 SEKISUI CHEMICAL CO., LTD.
- US5420068 A 19950530 NEC Corporation
- US6986941 B2 20060117 JSP Corporation
- WO2008008875 A2 20080117 DOW GLOBAL TECHNOLOGIES INC

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